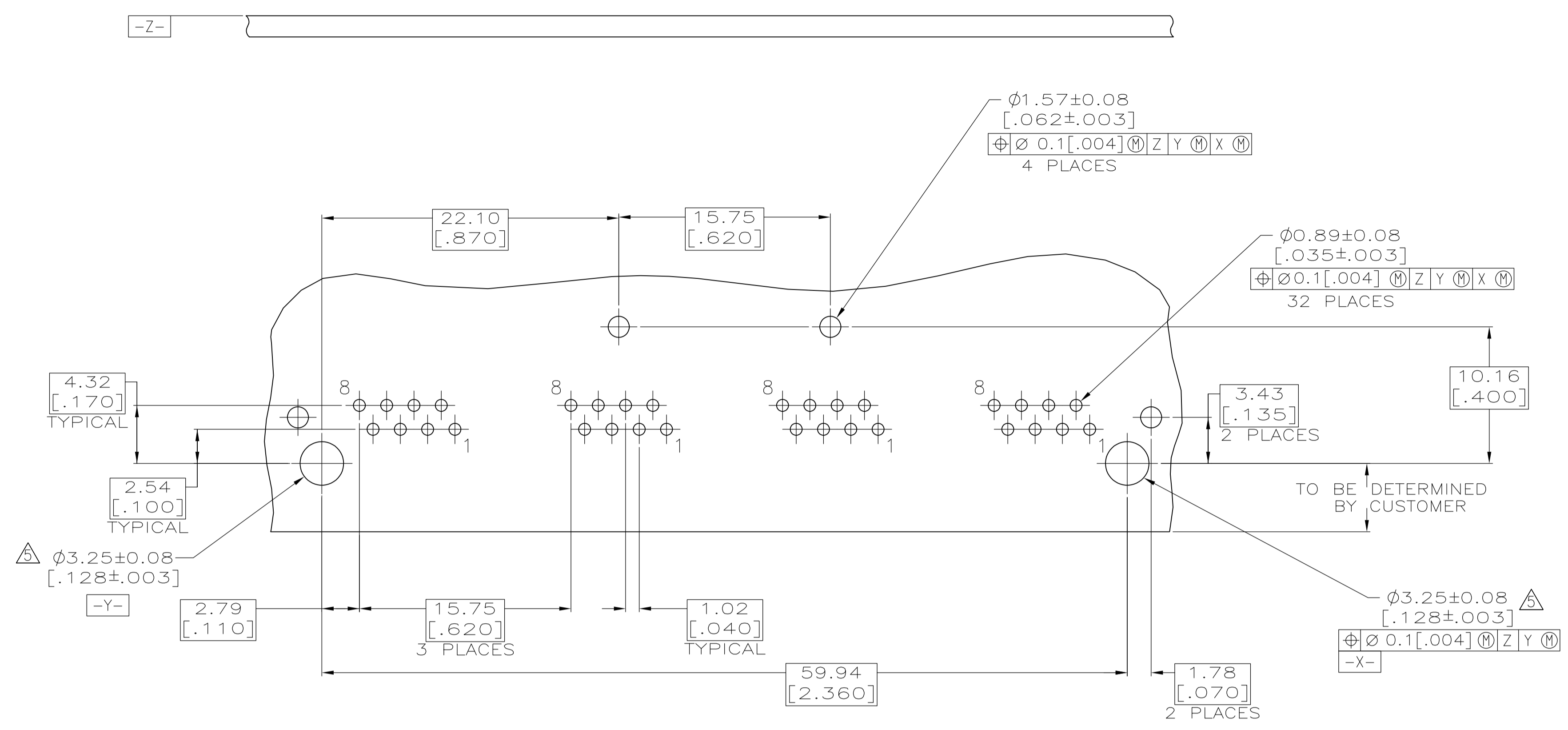
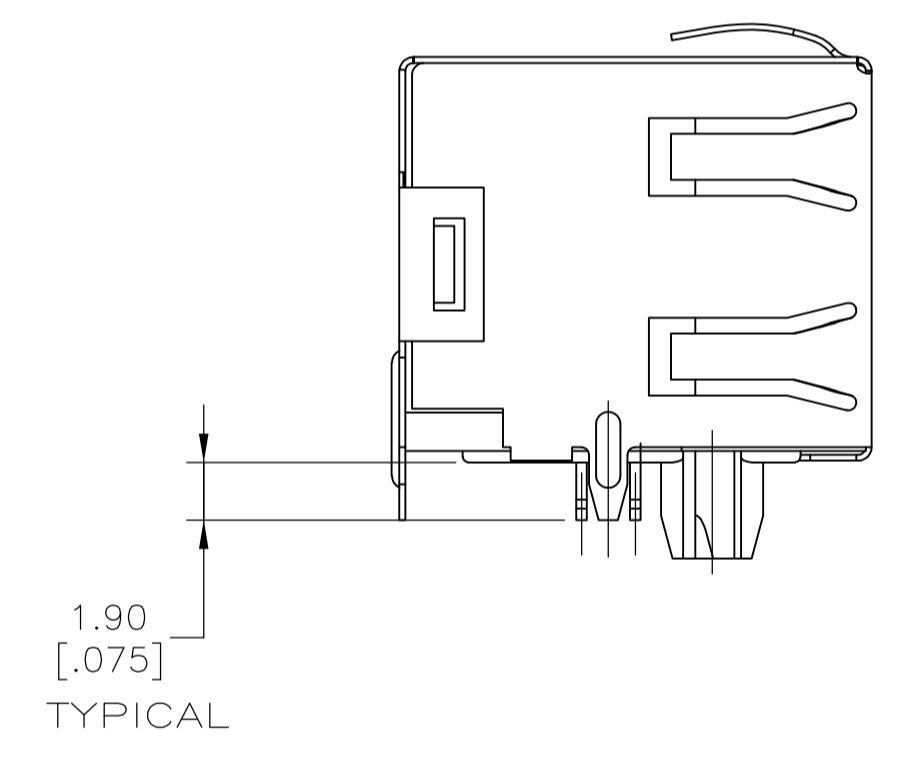
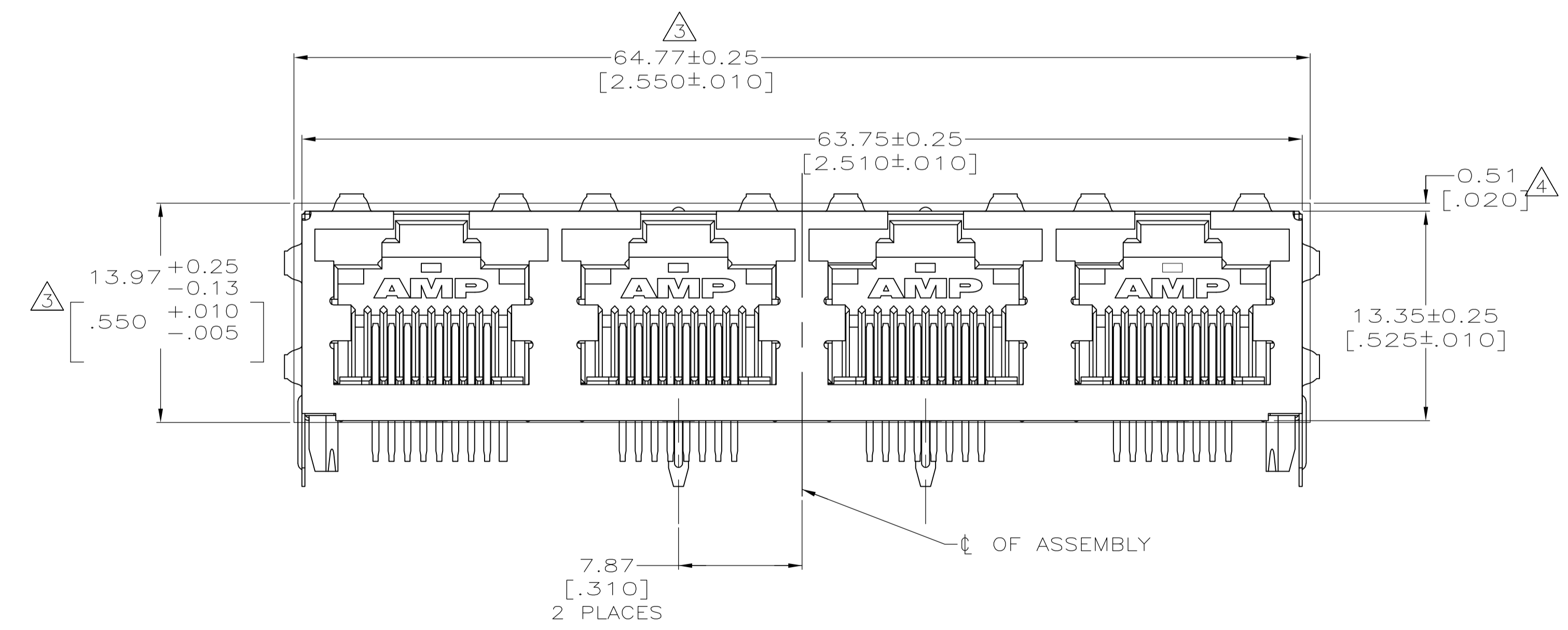
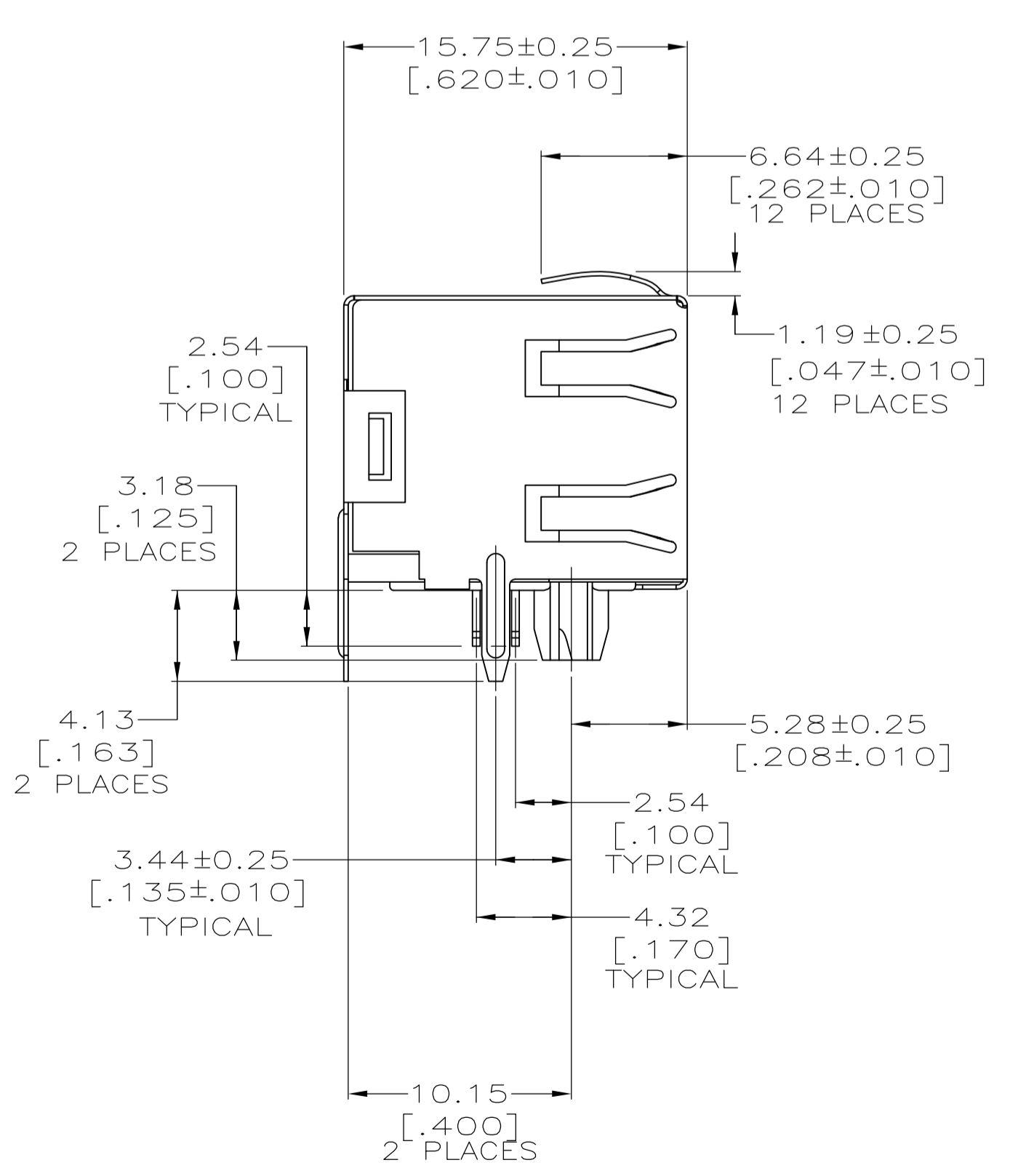


LOC	DIST	REVISIONS						
AA	22	REV	PER	ECO	DATE	BY	CHK	
		B1	REV	PER	ECO-14-011533	29JUL2014	CW	SH
		B3	PER	ECO-15-016408		28AUG15	AD	SH



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



ONLY FOR 5406544-3

- ⚠ MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μ m [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μ m [.000050] MINIMUM THICK NICKEL.
SHIELD - .196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μ m [.0000500] MIN NICKEL WITH 2.03 μ m [.000080] -3.81 μ m [.000150] POST DIP TION ON PCB GROUND TABS.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.
- ⚠ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- ⚠ PLEASE ENSURE THE HOLE IS FULL CIRCLE SHAPE
- ⚠ CAPABLE WITH LEAD FREE IR-REFLOW SOLDERING PROCESS.

TRAY	5406544-3
T&R	5406544-2
TRAY	5406544-1
PACKAGE	PART NUMBER

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		DIN		CIR		APVD		NAME	
mm	[INCHES]	0 PLC	± -	1 PLC	± -	J. ALCORTA	16JUN2005	S. WESTMAN	16JUN2005	108-1163-4	INVERTED MOD JACK ASSEMBLY, 1x4, SHIELDED, PANEL GROUND
		2 PLC	± 0.25[.01]	3 PLC	± 0.13[.005]					114-2154	
		4 PLC	± -	ANGLES	± -						
MATERIAL		FINISH	-	WEIGHT	-	SCALE	4:1	SHEET	1 OF 1	REV	B3
CUSTOMER DRAWING											

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)